PMP7154 REV C Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C2	1	330uF	EEEFK1V331P	Panasonic	Capacitor, Aluminum, 330µF, 850mArms	0.457 x 0.406
C3, C4	2	22uF	GRM32ER71E226KE15L	Murata	Capacitor, Ceramic, 22-uF, 25-V, X7R, 15%	1210
C5	1	100pF	Std	TDK	Capacitor, Ceramic, 100-pF, 50-V, X7R, 15%	0603
C6	1	33nF	Std	TDK	Capacitor, Ceramic, 33000-pF, 50-V, X7R, 15%	0603
C7	1		Std	TDK	Capacitor, Ceramic, 330-pF, 50-V, X7R, 15%	0603
C8, C14, C112	3	100nF	Std	TDK	Capacitor, Ceramic, 0.1-uF, 50-V, X7R, 15%	0603
C11, C12	2	100uF	C3225X5R0J107M	TDK	Capacitor, Ceramic, 100-uF, X5R, 15%	1210
C13, C111	2	470pF	Std	TDK	Capacitor, Ceramic, 470-pF, 50-V, X7R, 15%, Capacitor, Ceramic, 1n-F, 50-V, X7R, 15%	0603
C15	1	8.2nF	Std	TDK	Capacitor, Ceramic, 8200-pF, 50-V, X7R, 15%	0603
D1	1	B330-13	B330-13	DIODES inc.	Diode, Schottky, 3A, 30V	SMC
J1, J2	2	ED1514	ED1514	OST	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25
L2	1	47uH	7447714470	WE	Inductor, 99milliOhm, 2.2Arms, 2.5Asat	10.3 x 10.5 mm
L111	1	2.2uH	MSS5131-222MLC	Coilcraft	Inductor, SMT, 2-A, 17-milliohm	0.200 x 0.200 inch
Q2	1	FDC654P			MOSFET, P-ch, -30-V, 3.6-A, 75-milliOhms	Micro6
R1	1	68.1k	Std	Std	Resistor, Chip, 68.1K-Ohms, 1/16-W, 1%	0603
R2	1	0.05	CRCW1206-xxxx-F	Vishay	Resistor, Chip, 1/8W, 1%	1206
R3	1		Std	Std	Resistor, Chip, 2.2-Ohms, 1/16-W, 1%	0603
R4	1	0	Std	Std	Resistor, Chip, 0-Ohms, 1/16-W, 1%	0603
R5	1	4.02k	Std	Std	Resistor, Chip, 2.87K-Ohms, 1/16-W, 1%	0603
R6	1		Std	Std	Resistor, Chip, 150-Ohms, 1/16-W, 1%	0603
R7	1	10K	Std	Std	Resistor, Chip, 10K-Ohms, 1/16-W, 1%	0603
R8	1		Std	Std	Resistor, Chip, 49.9-Ohms, 1/16-W, 1%	0603
R9	1		Std	Std	Resistor, Chip, 16.2K-Ohms, 1/16-W, 1%	0603
R111	1	3.3	Std	Std	Resistor, Chip, 1/16W, x%	0805
TP1, TP3, TP4,	6		240-345	Farnell	Test Point, Red, 1mm	0.038
TP5, TP8, TP9						
TP2, TP6, TP7	3		240-333	Farnell	Test Point, Black, 1mm	0.038
U1	1	TPS40200D	TPS40200D	TI	IC, Low Cost Sync Buck Controller	SO-8

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